WHAT IS CLAIMED IS:

1. A method for removing an image sensor from a printed circuit board, the printed circuit board having a first surface and a second surface, the image sensor being welded to the first surface, and the method comprising the steps of:

supplying a hot air stream to the first surface of the printed circuit board so as to distribute the hot air stream over a periphery of the image sensor and to melt solder; and

providing a heater to heat the second surface of the printed circuit board and to raise a temperature of the second surface of the printed circuit board.

2. The method according to claim 1, wherein a temperature of the hot air stream substantially ranges from 170 to 190 ℃.

3. The method according to claim 1, wherein the heater has a temperature substantially greater than 80 ℃.